



SOT883B

DFN1006B-3: leadless ultra small plastic package; 3 solder lands; body 1.0 x 0.6 x 0.37 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	DFN1006B-3
Package type industry code	DFN1006B-3
Package style descriptive code	SOT (small outline transistor)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	30-6-2011

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		0.55	-	0.6	0.65	mm
E	package width		0.95	-	1	1.05	mm
A	seated height		0.34	-	0.37	0.4	mm
e	nominal pitch		-	-	0.35	-	mm
n ₂	actual quantity of termination		-	-	3	-	



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2. Package outline

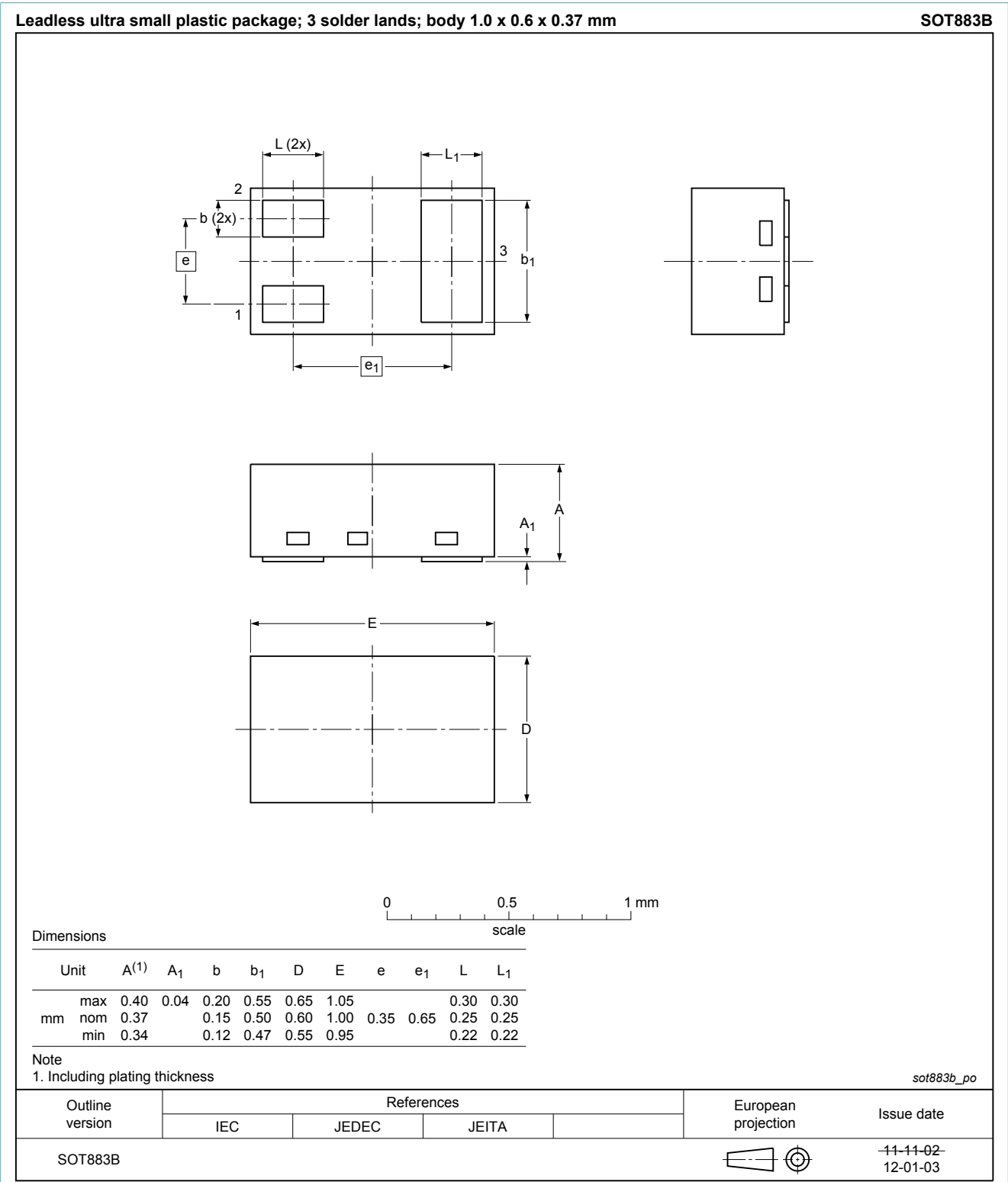


Fig. 1. Package outline DFN1006B-3 (SOT883B)

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3. Soldering

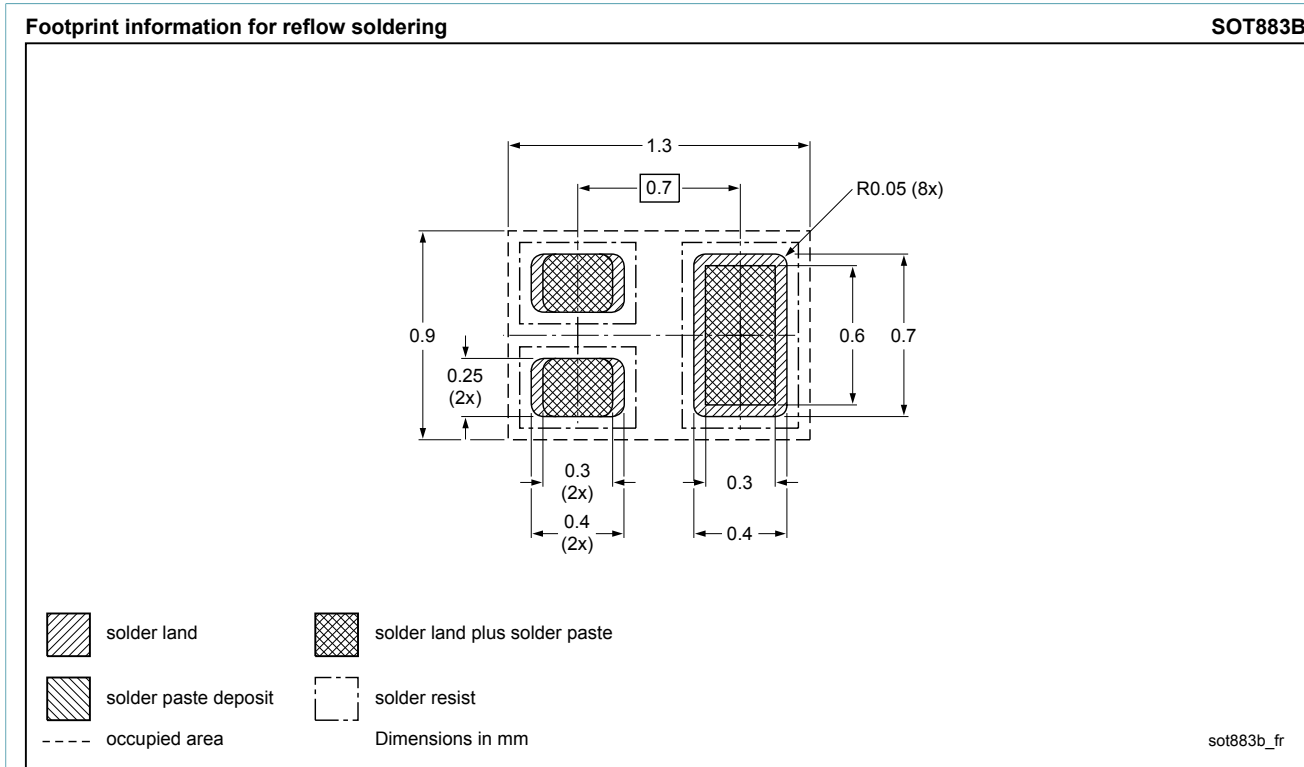


Fig. 2. Reflow soldering footprint for DFN1006B-3 (SOT883B)

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mm

4. Legal information

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